Electronic Pat	ent App	lication Fe	Transmit	tal			
Application Number:	10	10500196					
Filing Date:	10-	10-Oct-2006					
Title of Invention:	Me	Method and zone for sealing between two microstructure substrates					
First Named Inventor/Applicant Name:	Bei	Bernard Diem					
Filer:	Jas	Jasper W. Dockrey/Christine Pisarski					
Attorney Docket Number:	99	9905/23					
Filed as Large Entity							
U.S. National Stage under 35 USC 371 F	iling Fee	s					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:			'				
Pages:							
Claims:							
Claims in excess of 20		1615	2	52	104		
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension of Times							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			104